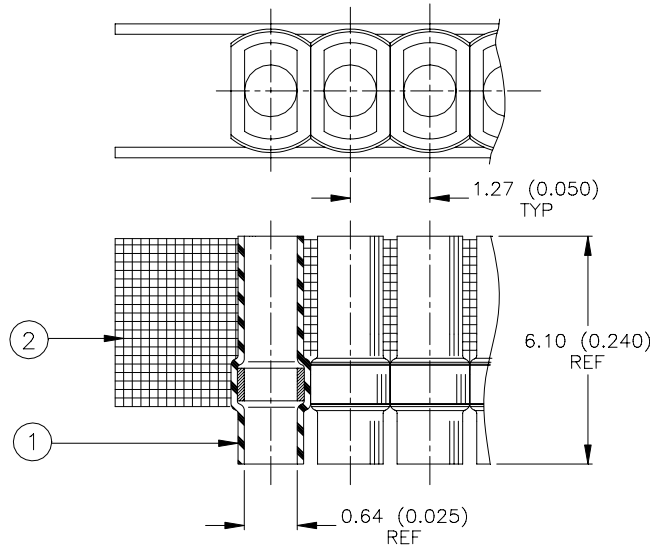


SPECIFICATION CONTROL DRAWING



MATERIALS

1. SOLDERSLLEEVE: D-141-22. Quantity Per Assembly: 1000
2. CARRIER STRIP: Adhesive Coated High Temperature Tape

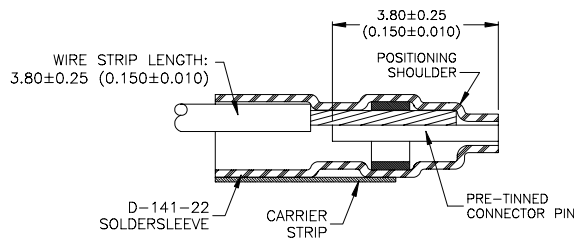
APPLICATION

1. This assembly is designed for use on micro-miniature connectors having a maximum pin cross sectional area envelope of 0.64 (0.025) diameter on 1.27 (0.050) center spacing.
2. Sleeves are to be installed using Raychem-approved convection or infrared heating tools.
3. The sleeves can accommodate the following wire sizes:

<u>No. of Wires</u>	<u>Wire Size (AWG)</u>
1	26
1	28
1	30
2	28 [0.81 (0.032) max. insulation O.D., 0.20 x 0.58 (0.008 x 0.023) pin]
2	30

4. Strip wires to 3.80 ± 0.25 (0.150 ± 0.010) and position as shown.
5. Trim pre-tinned connector pins, as required to 3.80 ± 0.25 (0.150 ± 0.010).
6. Remove forward carrier strip after sleeves have been positioned on pins prior to termination. Rear carrier strip is to be removed upon completion of termination.

Soldersleeve and Lead in Position for Assembly



tyco / Electronics / Raychem 307 Constitution Drive Menlo Park, CA 94025, USA		Wire and Harnessing Products	TITLE : SOLDERPAK ASSEMBLY, MICROMINIATURE CONNECTORS 1.27 (0.050) Center Spacing				
Unless otherwise specified dimensions are in millimeters. Inches dimensions are in between brackets.			DOCUMENT NO.: D-713-02				
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.	DCR NUMBER: D010415		REPLACES: N/A		
DRAWN BY: M. FORONDA	DATE: 22-Jun-01	PROD. REV. B	DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 1	

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